

Device Modeling Report

COMPONENTS: Power MOSFET (Professional Model)
PART NUMBER: 2SK4078
MANUFACTURER: NEC
Body Diode: (Professional Model)



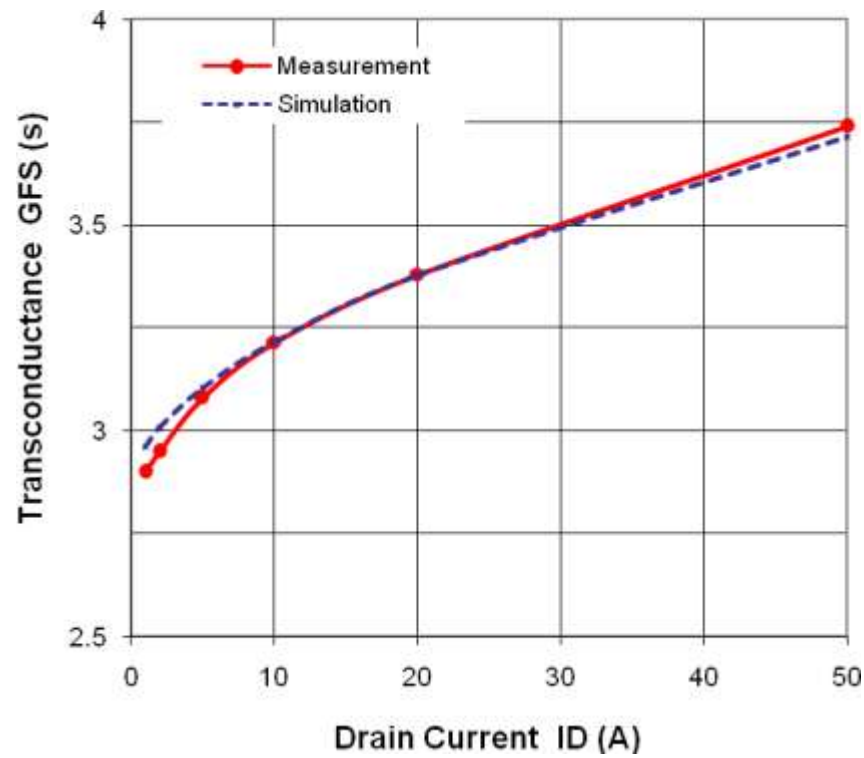
Bee Technologies Inc.

MOSFET MODEL

PSpice model parameter	Model description
LEVEL	
L	Channel Length
W	Channel Width
KP	Transconductance
RS	Source Ohmic Resistance
RD	Ohmic Drain Resistance
VTO	Zero-bias Threshold Voltage
RDS	Drain-Source Shunt Resistance
TOX	Gate Oxide Thickness
CGSO	Zero-bias Gate-Source Capacitance
CGDO	Zero-bias Gate-Drain Capacitance
CBD	Zero-bias Bulk-Drain Junction Capacitance
MJ	Bulk Junction Grading Coefficient
PB	Bulk Junction Potential
FC	Bulk Junction Forward-bias Capacitance Coefficient
RG	Gate Ohmic Resistance
IS	Bulk Junction Saturation Current
N	Bulk Junction Emission Coefficient
RB	Bulk Series Resistance
PHI	Surface Inversion Potential
GAMMA	Body-effect Parameter
DELTA	Width effect on Threshold Voltage
ETA	Static Feedback on Threshold Voltage
THETA	Mobility Modulation
KAPPA	Saturation Field Factor
VMAX	Maximum Drift Velocity of Carriers
XJ	Metallurgical Junction Depth
UO	Surface Mobility

Transconductance Characteristic

Circuit Simulation Result

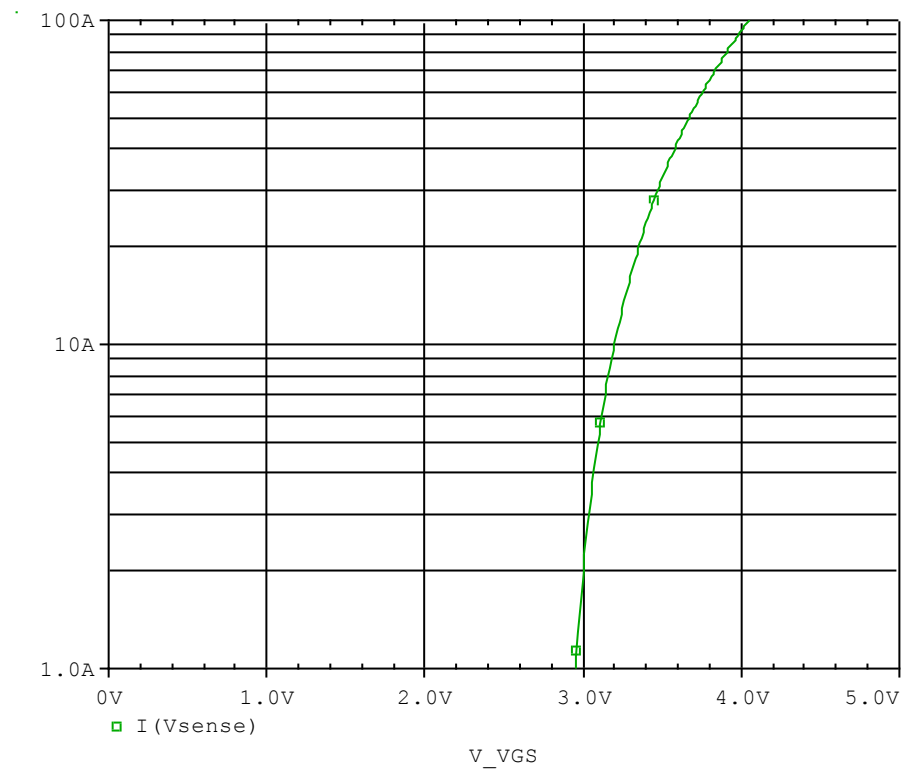


Comparison table

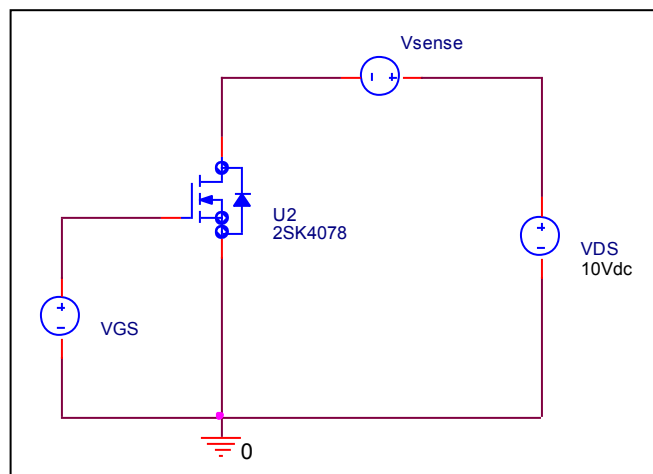
Id(A)	gfs		Error(%)
	Measurement	Simulation	
1.00	2.900	2.961	2.09
2.00	2.950	3.009	1.99
5.00	3.080	3.105	0.82
10.00	3.215	3.217	0.05
20.00	3.380	3.378	-0.05
50.00	3.740	3.713	-0.71

Vgs-Id Characteristic

Circuit Simulation result

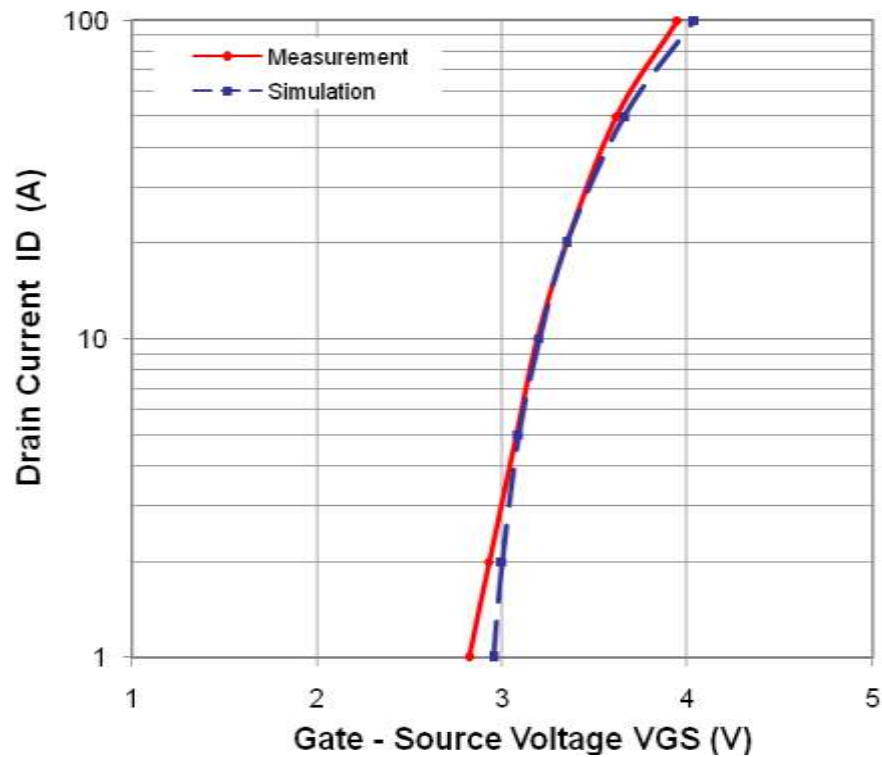


Evaluation circuit



Comparison Graph

Circuit Simulation Result

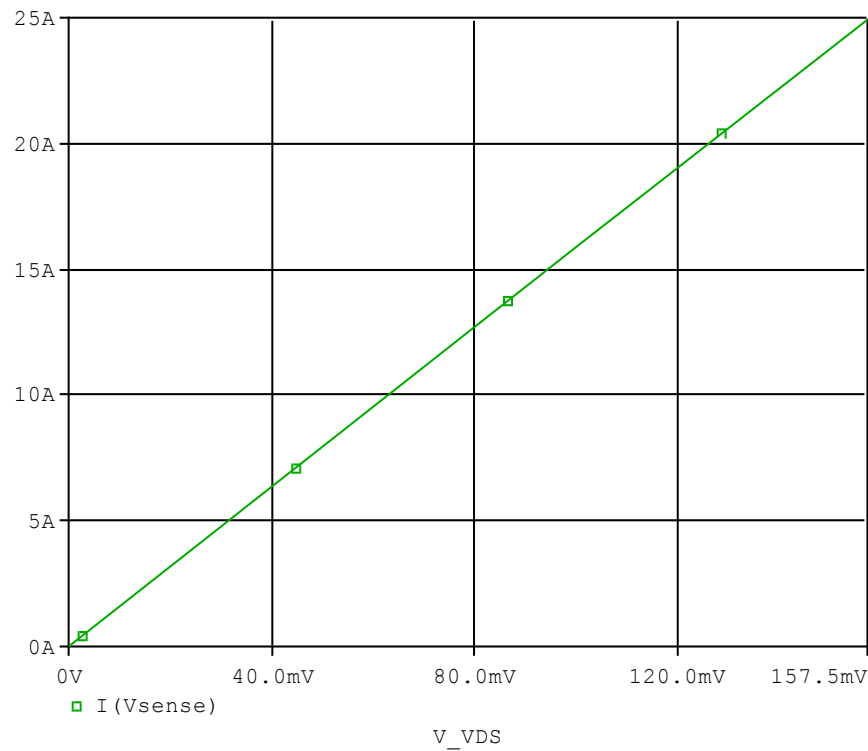


Simulation Result

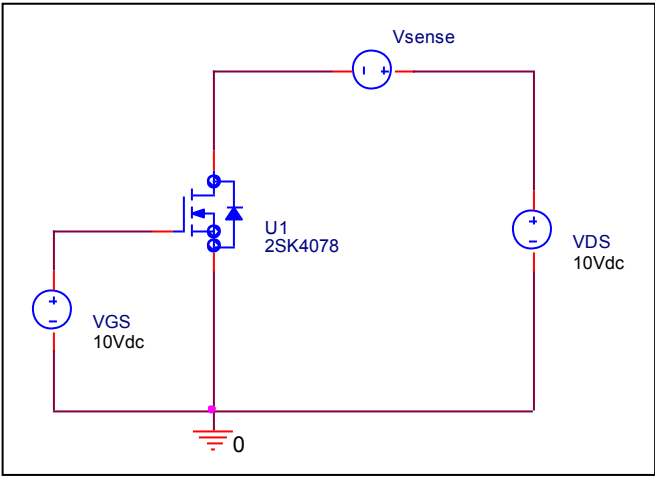
I _D (A)	V _{GS} (V)		Error (%)
	Measurement	Simulation	
1.00	2.825	2.955	4.61
2.00	2.930	3.000	2.39
5.00	3.080	3.090	0.32
10.00	3.190	3.200	0.31
20.00	3.348	3.350	0.06
50.00	3.615	3.660	1.24
100.00	3.950	4.040	2.28

Rds(on) Characteristic

Circuit Simulation result



Evaluation circuit

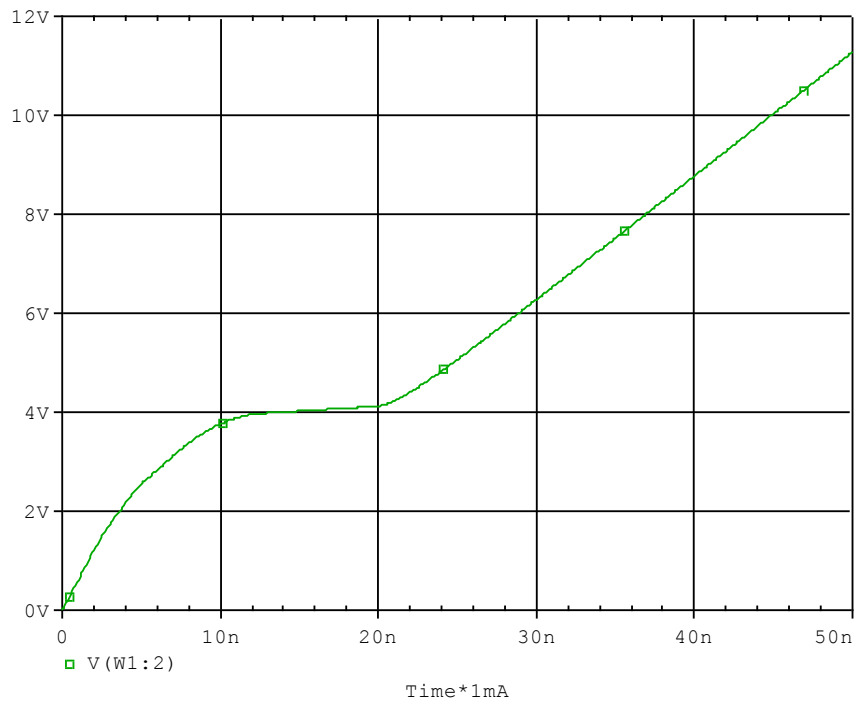


Simulation Result

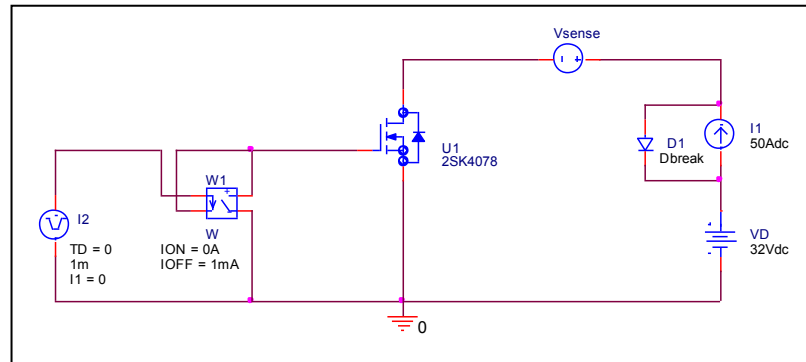
$I_D = 25A, V_{GS} = 10V$		Measurement	Simulation	Error (%)
$R_{DS(on)}$	m Ω	6.3	6.3	0.00

Gate Charge Characteristic

Circuit Simulation result



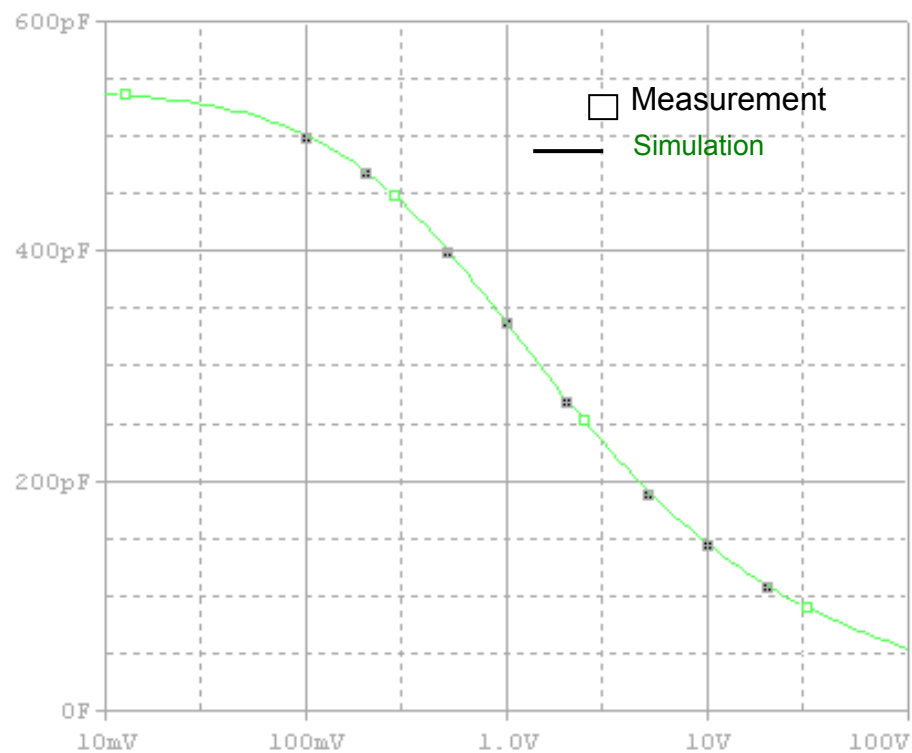
Evaluation circuit



Simulation Result

$V_{DD}=32V, I_D=50A, V_{GS}=10V$		Measurement	Simulation	Error (%)
Qgs	nC	7.00	6.96	-0.57
Qgd	nC	13.00	12.92	-0.62
Qg	nC	45.00	44.84	-0.36

Capacitance Characteristic

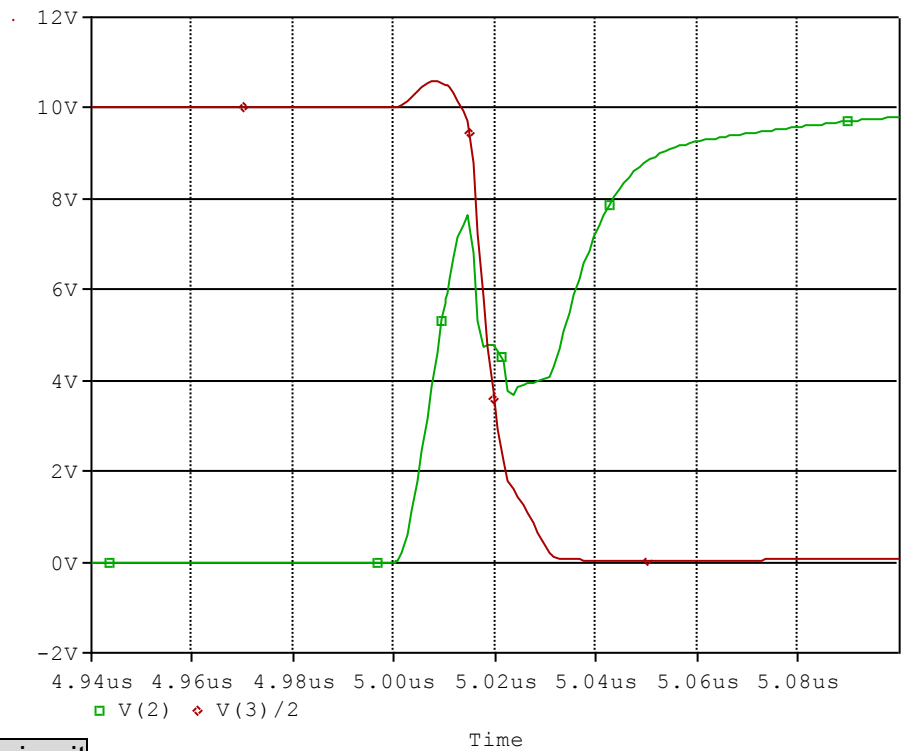


Simulation Result

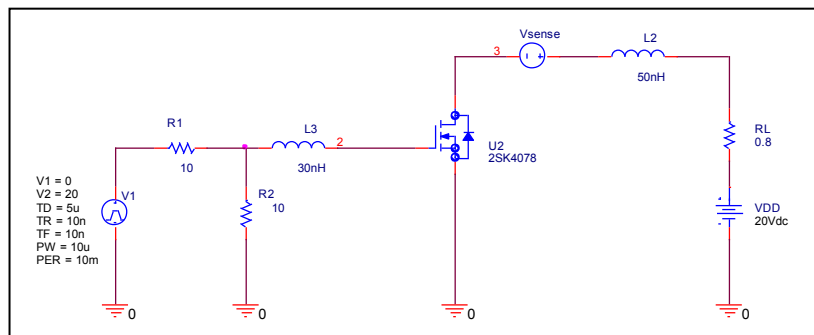
V_{DS} (V)	Cbd (pF)		Error(%)
	Measurement	Simulation	
0.100	500.00	510.00	-1.96
0.200	470.00	475.00	-1.05
0.500	400.00	403.00	-0.74
1.000	340.00	342.00	-0.58
2.000	270.00	271.00	-0.37
5.000	190.00	192.00	-1.04
10.000	145.00	147.00	-1.36
20.000	110.00	113.00	-2.65

Switching Time Characteristic

Circuit Simulation result



Evaluation circuit

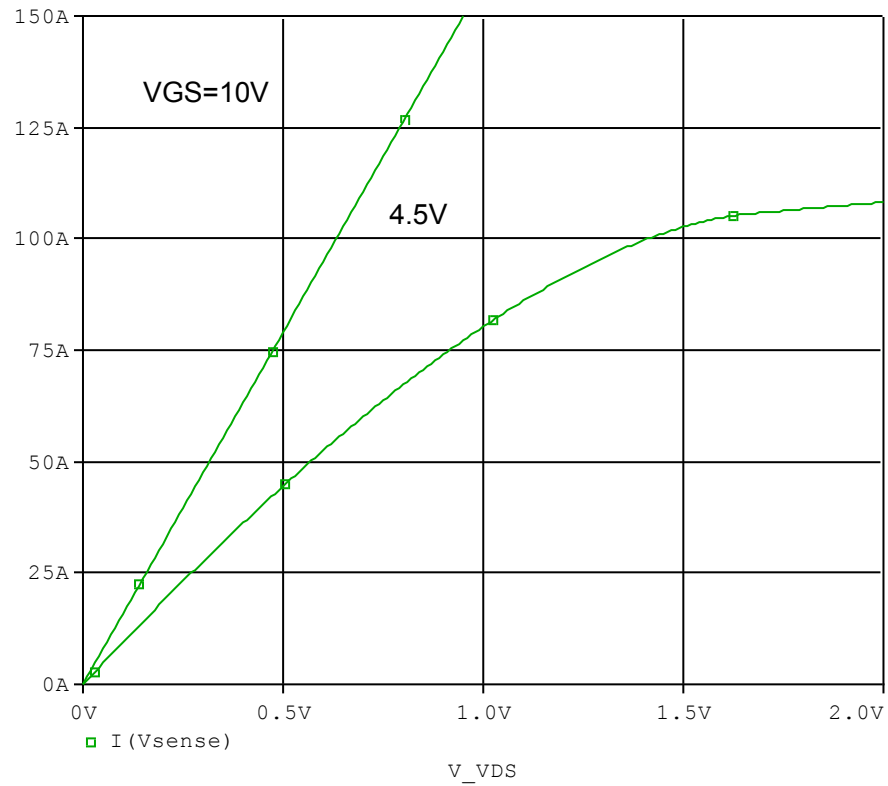


Simulation Result

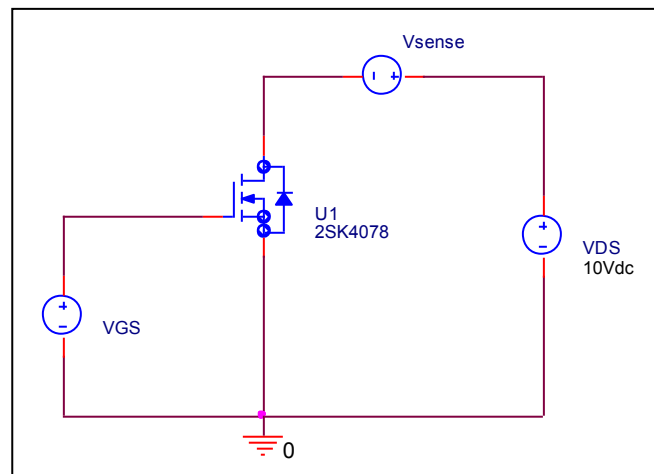
$I_D=25A, V_{DD}=20V$ $V_{GS}=0/10V$		Measurement	Simulation	Error(%)
td(on)	ns	12.00	11.97	-0.25

Output Characteristic

Circuit Simulation result

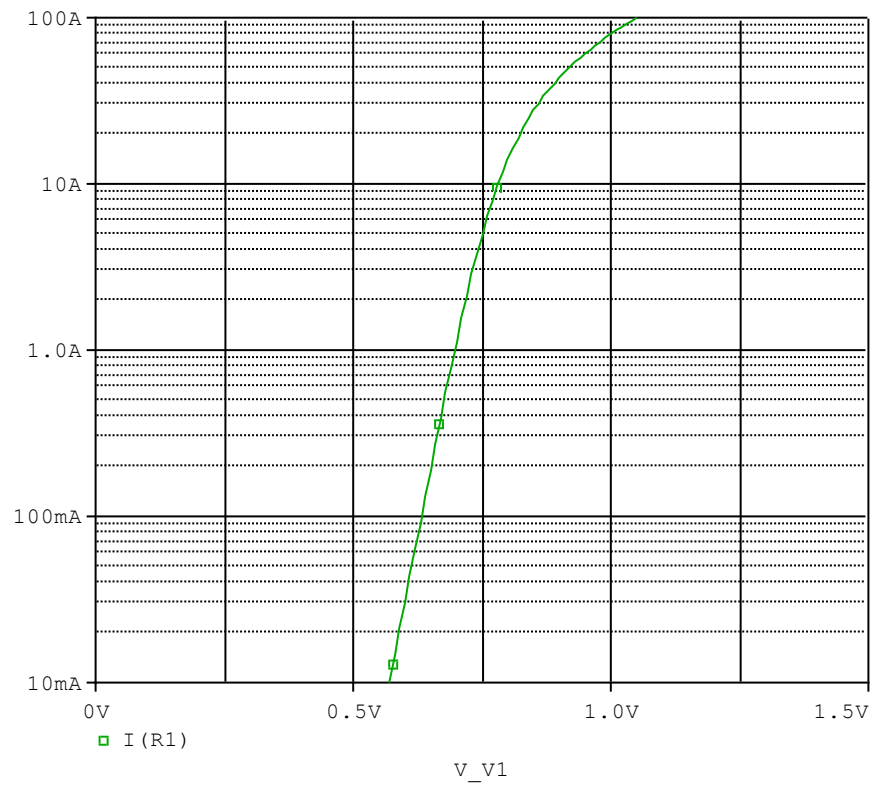


Evaluation circuit

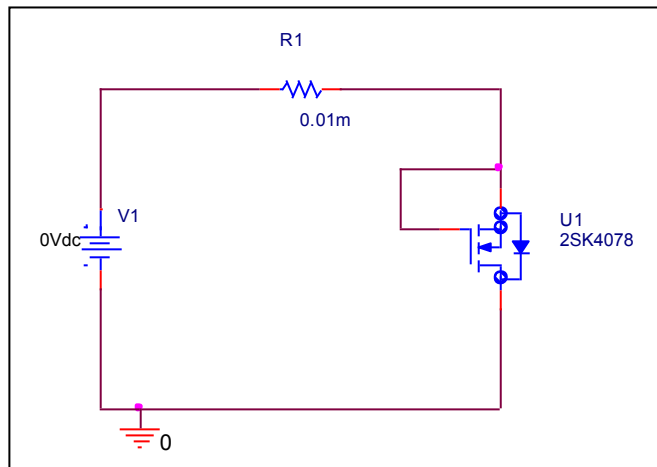


Forward Current Characteristic

Circuit Simulation Result

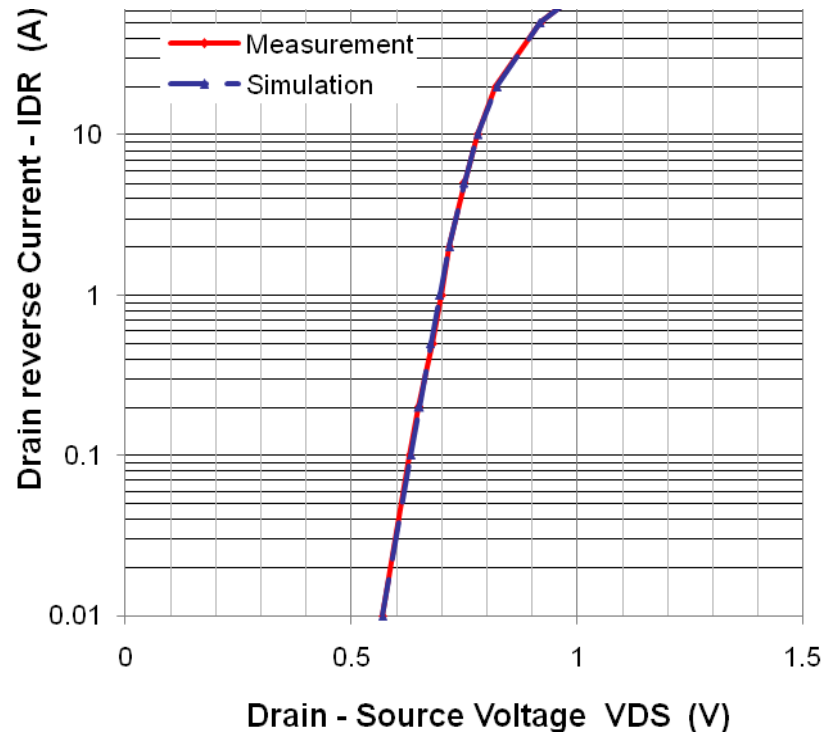


Evaluation Circuit



Comparison Graph

Circuit Simulation Result

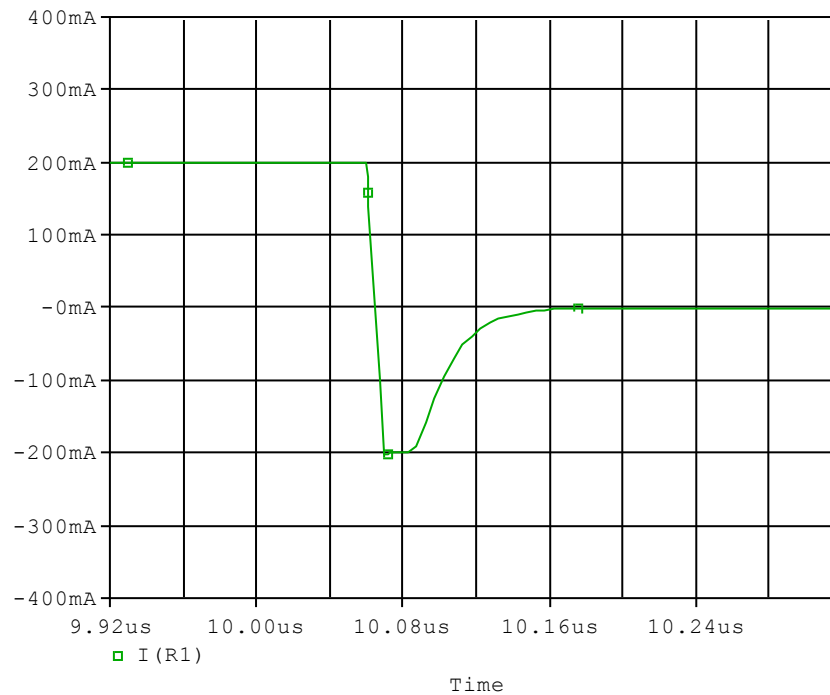


Simulation Result

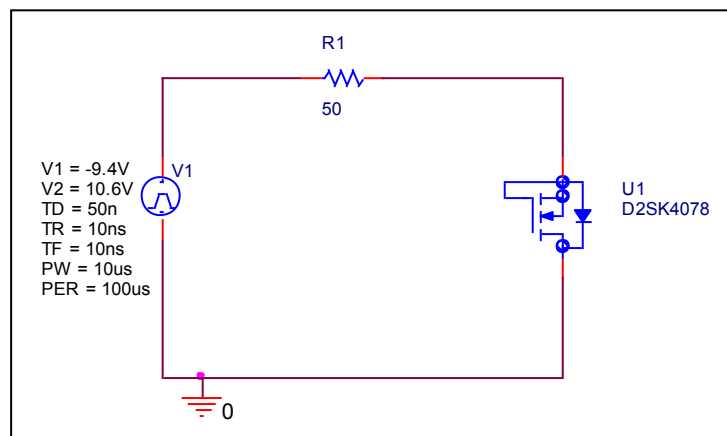
IDR(A)	VSD(V)		%Error
	Measurement	Simulation	
0.01	0.570	0.569	-0.18
0.10	0.630	0.632	0.32
0.20	0.650	0.651	0.15
0.50	0.680	0.676	-0.59
1.00	0.700	0.696	-0.57
2.00	0.718	0.717	-0.14
5.00	0.750	0.750	0.00
10.00	0.780	0.780	0.00
20.00	0.820	0.823	0.37
50.00	0.920	0.918	-0.17
100.00	1.050	1.051	0.12

Reverse Recovery Characteristics (Body Diode)

Circuit Simulation Result



Evaluation Circuit

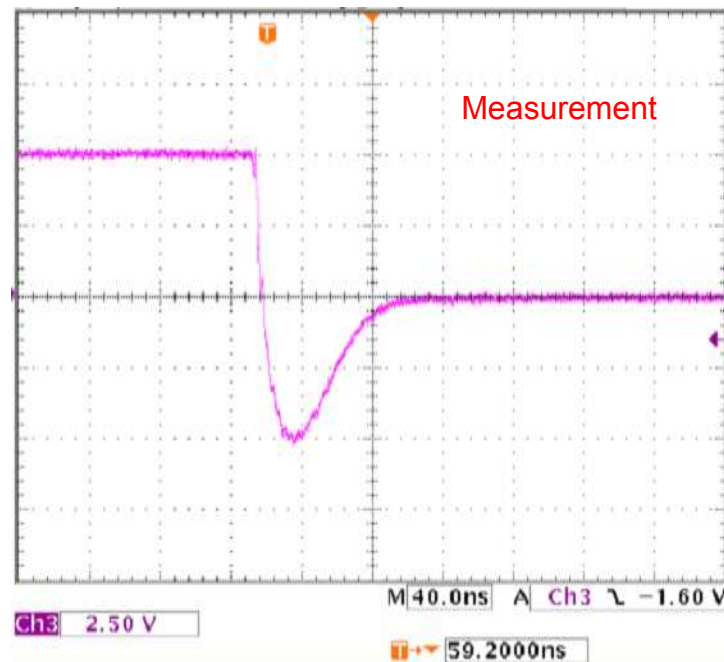


Compare Measurement vs. Simulation

		Measurement	Simulation	Error (%)
trj	ns	19.20	19.33	0.68
trb	ns	44.80	44.61	-0.42
trr	ns	64.00	63.94	-0.09

Reverse Recovery Characteristic

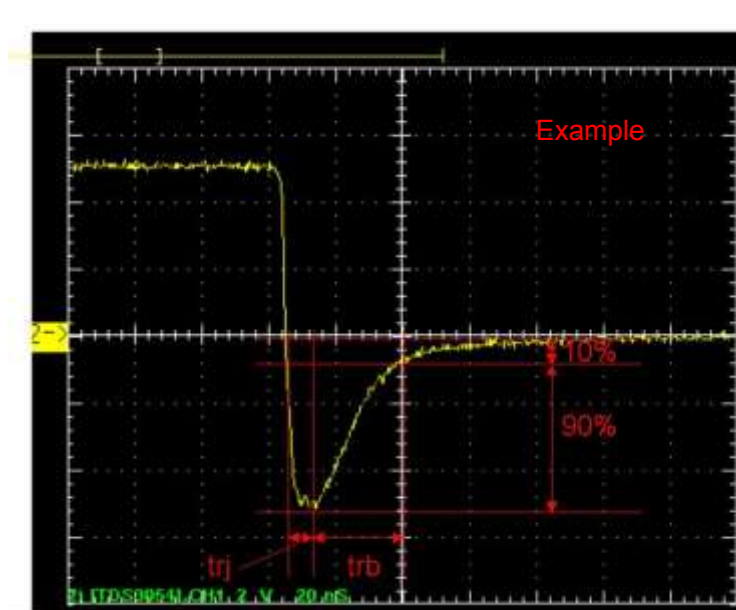
Reference



$T_{rj}=19.2(\text{ns})$

$T_{rb}=44.8(\text{ns})$

Conditions: $I_{fwd}=I_{rev}=0.2(\text{A})$, $R_I=50$



Relation between t_{rj} and t_{rb}